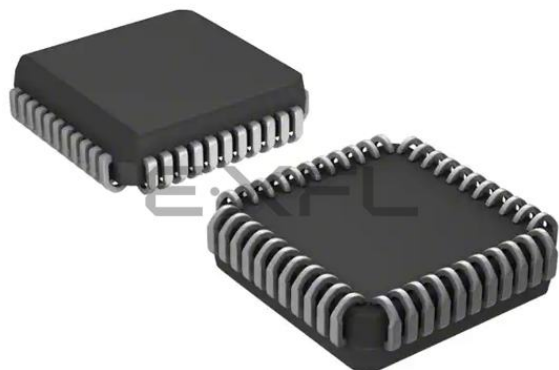




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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	-
Number of Macrocells	64
Number of Gates	-
Number of I/O	32
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m4a3-64-32-10jni

The ispMACH 4A family offers 20 density-I/O combinations in Thin Quad Flat Pack (TQFP), Plastic Quad Flat Pack (PQFP), Plastic Leaded Chip Carrier (PLCC), Ball Grid Array (BGA), fine-pitch BGA (fpBGA), and chip-array BGA (caBGA) packages ranging from 44 to 388 pins (Table 3). It also offers I/O safety features for mixed-voltage designs so that the 3.3-V devices can accept 5-V inputs, and 5-V devices do not overdrive 3.3-V inputs. Additional features include Bus-Friendly inputs and I/Os, a programmable power-down mode for extra power savings and individual output slew rate control for the highest speed transition or for the lowest noise transition.

Table 3. ispMACH 4A Package and I/O Options (Number of I/Os and dedicated inputs in Table)

3.3 V Devices								
Package	M4A3-32	M4A3-64	M4A3-96	M4A3-128	M4A3-192	M4A3-256	M4A3-384	M4A3-512
44-pin PLCC	32+2	32+2						
44-pin TQFP	32+2	32+2						
48-pin TQFP	32+2	32+2						
100-pin TQFP		64+6	48+8	64+6				
100-pin PQFP				64+6				
100-ball caBGA				64+6				
144-pin TQFP					96+16			
144-ball fpBGA					96+16			
208-pin PQFP						128+14, 160	160	160
256-ball fpBGA						128+14, 192	192	192
256-ball BGA						128+14	192	
388-ball fpBGA								256

5 V Devices						
Package	M4A5-32	M4A5-64	M4A5-96	M4A5-128	M4A5-192	M4A5-256
44-pin PLCC	32+2	32+2				
44-pin TQFP	32+2	32+2				
48-pin TQFP	32+2	32+2				
100-pin TQFP			48+8	64+6		
100-pin PQFP				64+6		
144-pin TQFP					96+16	
208-pin PQFP						128+14

Product-Term Array

The product-term array consists of a number of product terms that form the basis of the logic being implemented. The inputs to the AND gates come from the central switch matrix (Table 5), and are provided in both true and complement forms for efficient logic implementation.

Table 5. PAL Block Inputs

Device	Number of Inputs to PAL Block
M4A3-32/32 and M4A5-32/32	33
M4A3-64/32 and M4A5-64/32	33
M4A3-64/64	33
M4A3-96/48 and M4A5-96/48	33
M4A3-128/64 and M4A5-128/64	33
M4A3-192/96 and M4A5-192/96	34
M4A3-256/128 and M4A5-256/128	34
M4A3-256/160 and M4A3-256/192	36
M4A3-384	36
M4A3-512	36

Logic Allocator

Within the logic allocator, product terms are allocated to macrocells in “product term clusters.” The availability and distribution of product term clusters are automatically considered by the software as it fits functions within a PAL block. The size of a product term cluster has been optimized to provide high utilization of product terms, making complex functions using many product terms possible. Yet when few product terms are used, there will be a minimal number of unused—or wasted—product terms left over. The product term clusters available to each macrocell within a PAL block are shown in Tables 6 and 7.

Each product term cluster is associated with a macrocell. The size of a cluster depends on the configuration of the associated macrocell. When the macrocell is used in synchronous mode (Figure 2a), the basic cluster has 4 product terms. When the associated macrocell is used in asynchronous mode (Figure 2b), the cluster has 2 product terms. Note that if the product term cluster is routed to a different macrocell, the allocator configuration is not determined by the mode of the macrocell actually being driven. The configuration is always set by the mode of the macrocell that the cluster will drive if not routed away, regardless of the actual routing.

In addition, there is an extra product term that can either join the basic cluster to give an extended cluster, or drive the second input of an exclusive-OR gate in the signal path. If included with the basic cluster, this provides for up to 20 product terms on a synchronous function that uses four extended 5-product-term clusters. A similar asynchronous function can have up to 18 product terms.

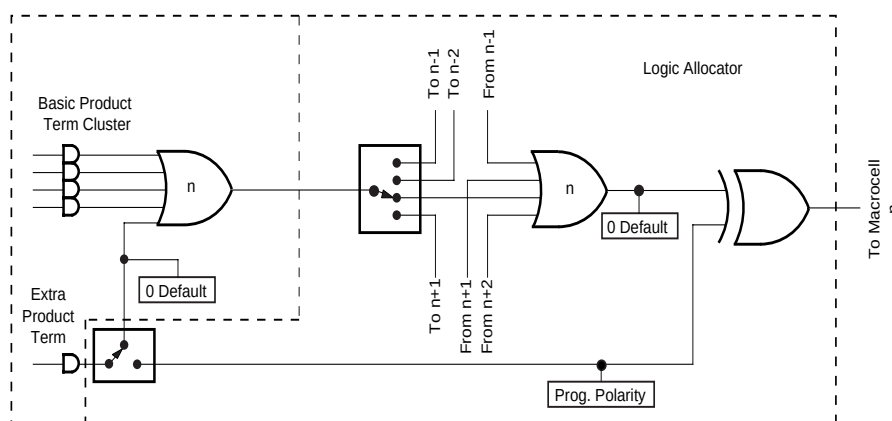
When the extra product term is used to extend the cluster, the value of the second XOR input can be programmed as a 0 or a 1, giving polarity control. The possible configurations of the logic allocator are shown in Figures 3 and 4.

Table 6. Logic Allocator for All ispMACH 4A Devices (except M4A(3,5)-32/32)

Output Macrocell	Available Clusters	Output Macrocell	Available Clusters
M ₀	C ₀ , C ₁ , C ₂	M ₈	C ₇ , C ₈ , C ₉ , C ₁₀
M ₁	C ₀ , C ₁ , C ₂ , C ₃	M ₉	C ₈ , C ₉ , C ₁₀ , C ₁₁
M ₂	C ₁ , C ₂ , C ₃ , C ₄	M ₁₀	C ₉ , C ₁₀ , C ₁₁ , C ₁₂
M ₃	C ₂ , C ₃ , C ₄ , C ₅	M ₁₁	C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃
M ₄	C ₃ , C ₄ , C ₅ , C ₆	M ₁₂	C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄
M ₅	C ₄ , C ₅ , C ₆ , C ₇	M ₁₃	C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅
M ₆	C ₅ , C ₆ , C ₇ , C ₈	M ₁₄	C ₁₃ , C ₁₄ , C ₁₅
M ₇	C ₆ , C ₇ , C ₈ , C ₉	M ₁₅	C ₁₄ , C ₁₅

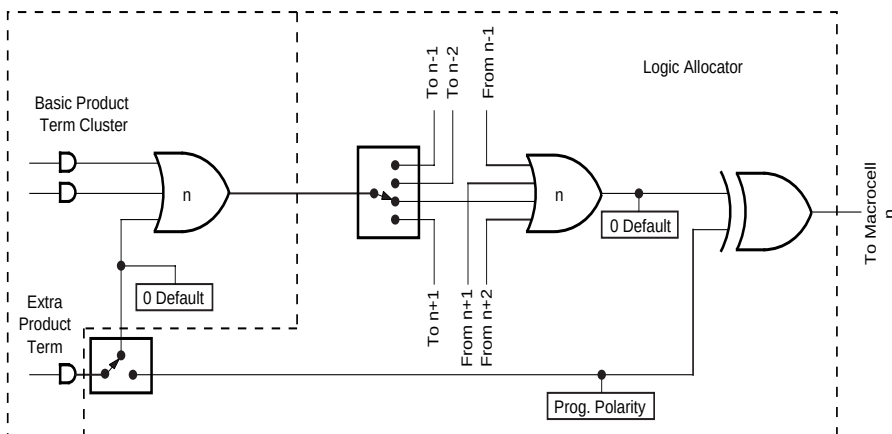
Table 7. Logic Allocator for M4A(3,5)-32/32

Output Macrocell	Available Clusters	Output Macrocell	Available Clusters
M ₀	C ₀ , C ₁ , C ₂	M ₈	C ₈ , C ₉ , C ₁₀
M ₁	C ₀ , C ₁ , C ₂ , C ₃	M ₉	C ₈ , C ₉ , C ₁₀ , C ₁₁
M ₂	C ₁ , C ₂ , C ₃ , C ₄	M ₁₀	C ₉ , C ₁₀ , C ₁₁ , C ₁₂
M ₃	C ₂ , C ₃ , C ₄ , C ₅	M ₁₁	C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃
M ₄	C ₃ , C ₄ , C ₅ , C ₆	M ₁₂	C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄
M ₅	C ₄ , C ₅ , C ₆ , C ₇	M ₁₃	C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅
M ₆	C ₅ , C ₆ , C ₇	M ₁₄	C ₁₃ , C ₁₄ , C ₁₅
M ₇	C ₆ , C ₇	M ₁₅	C ₁₄ , C ₁₅



a. Synchronous Mode

17466G-005



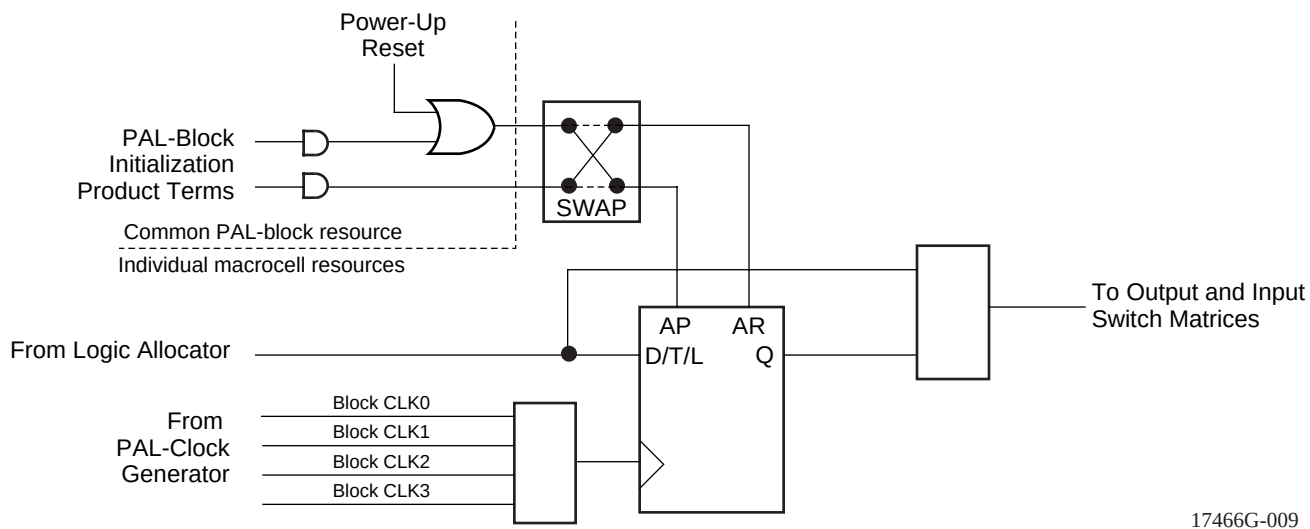
b. Asynchronous Mode

17466G-006

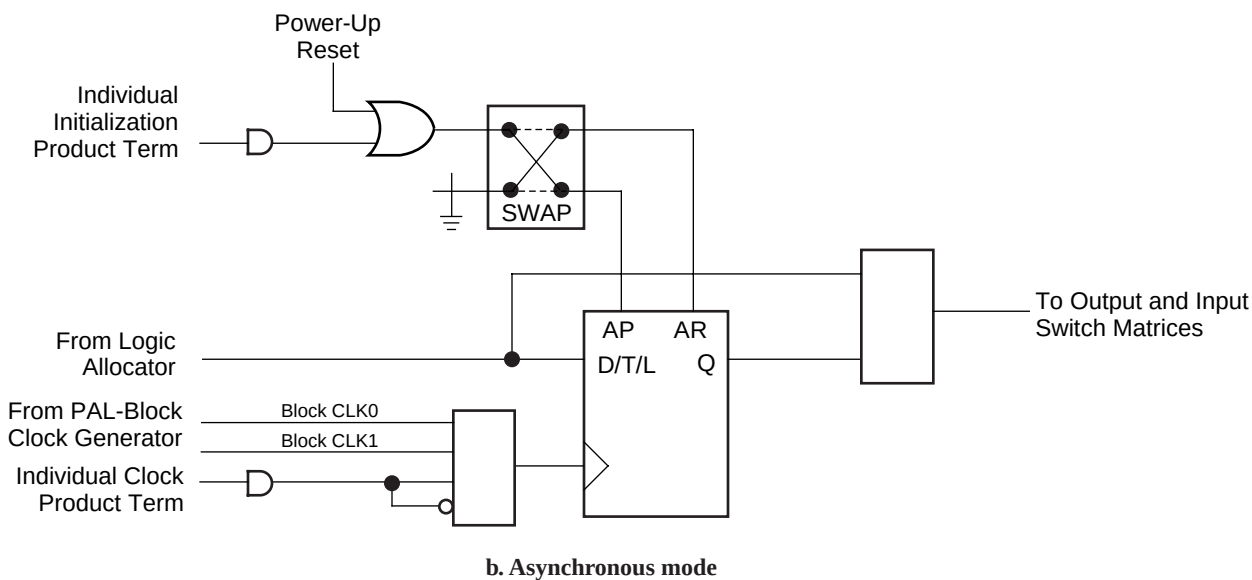
Figure 2. Logic Allocator: Configuration of Cluster “n” Set by Mode of Macrocell “n”

Macrocell

The macrocell consists of a storage element, routing resources, a clock multiplexer, and initialization control. The macrocell has two fundamental modes: synchronous and asynchronous (Figure 5). The mode chosen only affects clocking and initialization in the macrocell.



17466G-009

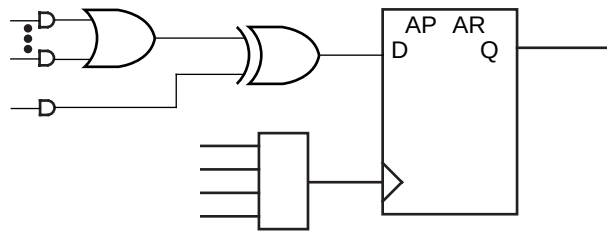


17466G-010

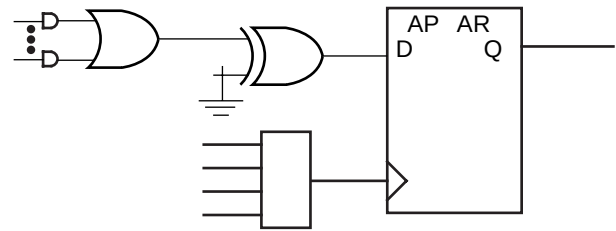
Figure 5. Macrocell

In either mode, a combinatorial path can be used. For combinatorial logic, the synchronous mode will generally be used, since it provides more product terms in the allocator.

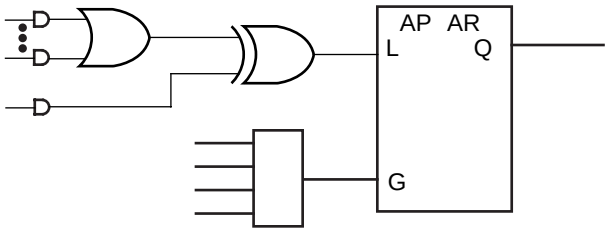
The flip-flop can be configured as a D-type or T-type latch. J-K or S-R registers can be synthesized. The primary flip-flop configurations are shown in Figure 6, although others are possible. Flip-flop functionality is defined in Table 8. Note that a J-K latch is inadvisable as it will cause oscillation if both J and K inputs are HIGH.



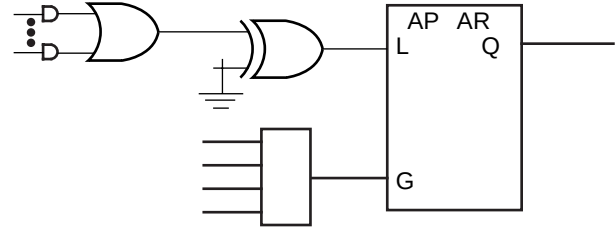
a. D-type with XOR



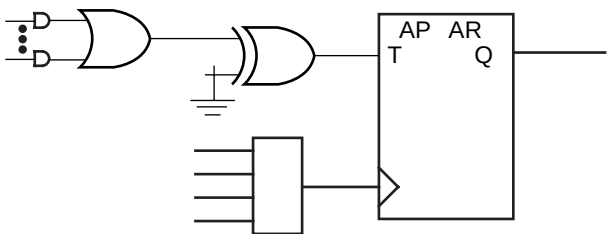
b. D-type with programmable D polarity



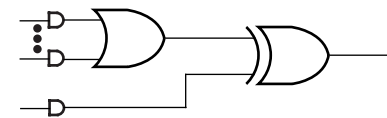
c. Latch with XOR



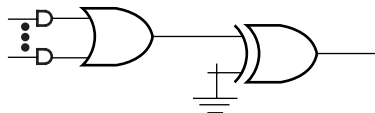
d. Latch with programmable D polarity



e. T-type with programmable T polarity



f. Combinatorial with XOR



g. Combinatorial with programmable polarity

Figure 6. Primary Macrocell Configurations

17466G-011

Table 10. Output Switch Matrix Combinations for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio

Macrocell	Routable to I/O Cells
M12, M13	I/O3, I/O4, I/O5, I/O6
M14, M15	I/O4, I/O5, I/O6, I/O7

I/O Cell	Available Macrocells
I/O0	M0, M1, M2, M3, M4, M5, M6, M7
I/O1	M2, M3, M4, M5, M6, M7, M8, M9
I/O2	M4, M5, M6, M7, M8, M9, M10, M11
I/O3	M6, M7, M8, M9, M10, M11, M12, M13
I/O4	M8, M9, M10, M11, M12, M13, M14, M15
I/O5	M0, M1, M10, M11, M12, M13, M14, M15
I/O6	M0, M1, M2, M3, M12, M13, M14, M15
I/O7	M0, M1, M2, M3, M4, M5, M14, M15

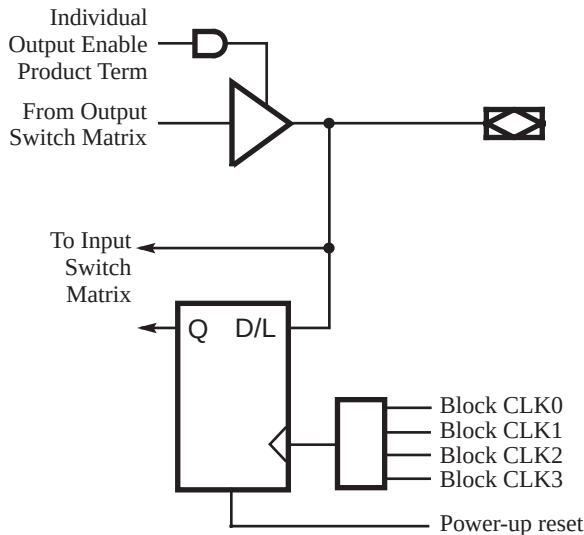
Table 11. Output Switch Matrix Combinations for M4A3-256/160 and M4A3-256/192

Macrocell	Routable to I/O Cells							
M0	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M1	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M2	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M3	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M4	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M5	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M6	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M7	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M8	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M9	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M10	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M11	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M12	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M13	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M14	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M15	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15

I/O Cell	Available Macrocells							
I/O0	M0	M1	M2	M3	M4	M5	M6	M7
I/O1	M0	M1	M2	M3	M4	M5	M6	M7
I/O2	M0	M1	M2	M3	M4	M5	M6	M7
I/O3	M0	M1	M2	M3	M4	M5	M6	M7
I/O4	M0	M1	M2	M3	M4	M5	M6	M7
I/O5	M0	M1	M2	M3	M4	M5	M6	M7
I/O6	M0	M1	M2	M3	M4	M5	M6	M7
I/O7	M0	M1	M2	M3	M4	M5	M6	M7

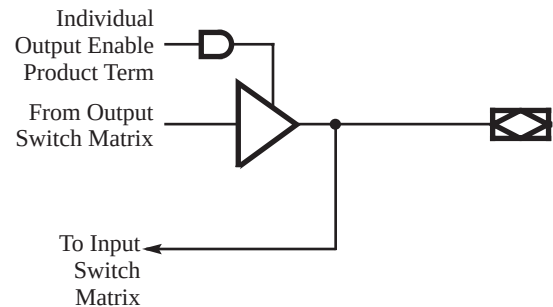
I/O Cell

The I/O cell (Figures 10 and 11) simply consists of a programmable output enable, a feedback path, and flip-flop (except ispMACH 4A devices with 1:1 macrocell-I/O cell ratio). An individual output enable product term is provided for each I/O cell. The feedback signal drives the input switch matrix.



17466G-017

Figure 10. I/O Cell for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio



17466G-018

Figure 11. I/O Cell for ispMACH 4A Devices with 1:1 Macrocell-I/O Cell Ratio

The I/O cell (Figure 10) contains a flip-flop, which provides the capability for storing the input in a D-type register or latch. The clock can be any of the PAL block clocks. Both the direct and registered versions of the input are sent to the input switch matrix. This allows for such functions as “time-domain-multiplexed” data comparison, where the first data value is stored, and then the second data value is put on the I/O pin and compared with the previous stored value.

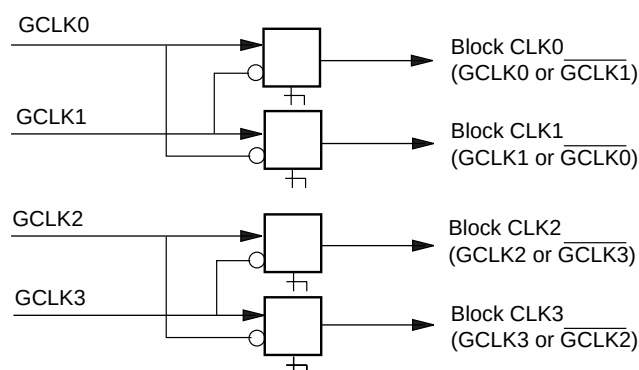
Note that the flip-flop used in the ispMACH 4A I/O cell is independent of the flip-flops in the macrocells. It powers up to a logic low.

Zero-Hold-Time Input Register

The ispMACH 4A devices have a zero-hold-time (ZHT) fuse which controls the time delay associated with loading data into all I/O cell registers and latches. When programmed, the ZHT fuse increases the data path setup delays to input storage elements, matching equivalent delays in the clock path. When the fuse is erased, the setup time to the input storage element is minimized. This feature facilitates doing worst-case designs for which data is loaded from sources which have low (or zero) minimum output propagation delays from clock edges.

PAL Block Clock Generation

Each ispMACH 4A device has four clock pins that can also be used as inputs. These pins drive a clock generator in each PAL block (Figure 14). The clock generator provides four clock signals that can be used anywhere in the PAL block. These four PAL block clock signals can consist of a large number of combinations of the true and complement edges of the global clock signals. Table 14 lists the possible combinations.



17466G-004

Figure 14. PAL Block Clock Generator¹

1. M4A(3,5)-32/32 and M4A(3,5)-64/32 have only two clock pins, GCLK0 and GCLK1. GCLK2 is tied to GCLK0, and GCLK3 is tied to GCLK1.

Table 14. PAL Block Clock Combinations¹

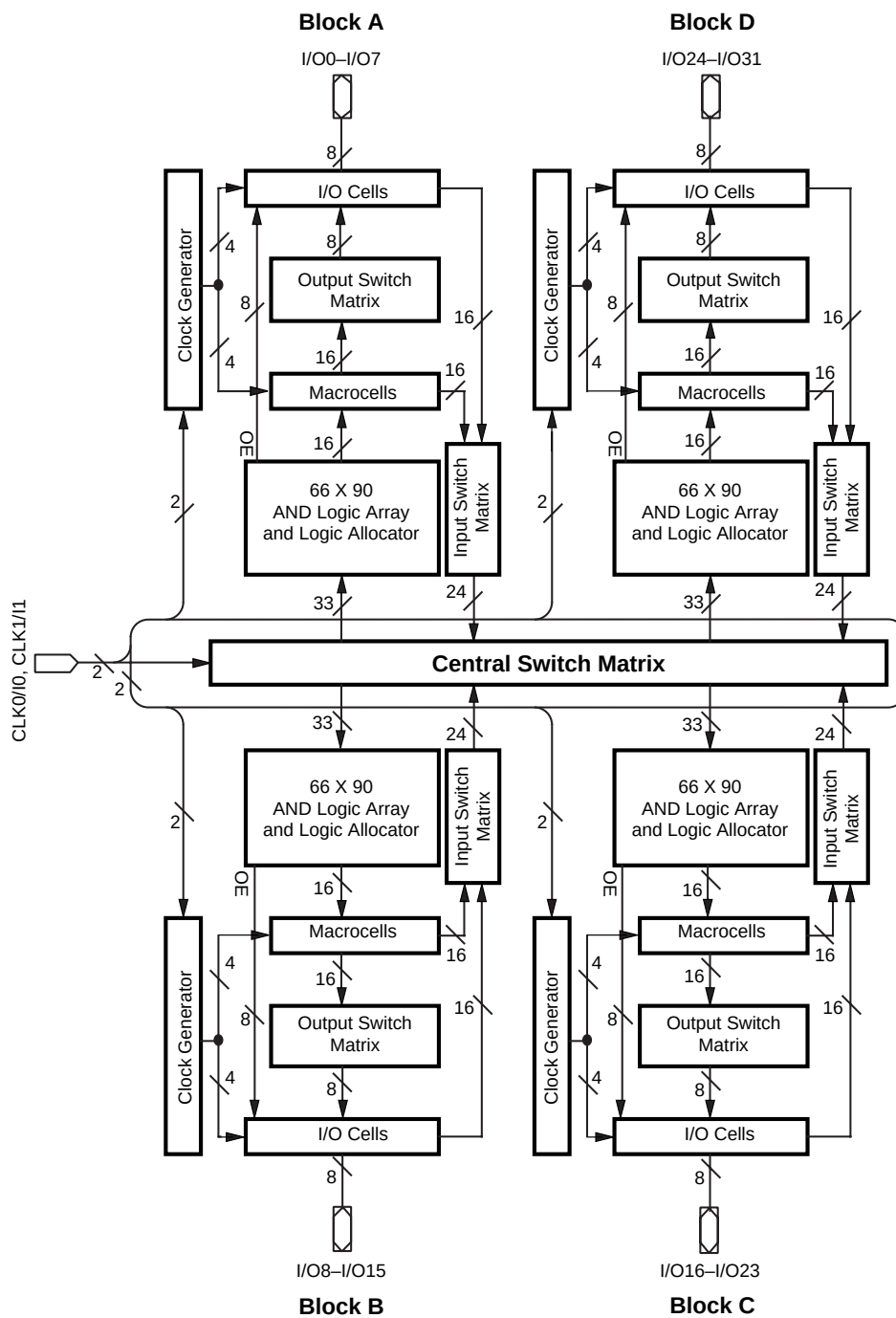
Block CLK0	Block CLK1	Block CLK2	Block CLK3
GCLK0	GCLK1	X	X
$\overline{\text{GCLK1}}$	GCLK1	X	X
GCLK0	$\overline{\text{GCLK0}}$	X	X
$\overline{\text{GCLK1}}$	$\overline{\text{GCLK0}}$	X	X
X	X	GCLK2 (GCLK0)	GCLK3 (GCLK1)
X	X	$\overline{\text{GCLK3}}$ ($\overline{\text{GCLK1}}$)	GCLK3 (GCLK1)
X	X	GCLK2 (GCLK0)	$\overline{\text{GCLK2}}$ ($\overline{\text{GCLK0}}$)
X	X	$\overline{\text{GCLK3}}$ (GCLK1)	$\overline{\text{GCLK2}}$ ($\overline{\text{GCLK0}}$)

Note:

1. Values in parentheses are for the M4A(3,5)-32/32 and M4A(3,5)-64/32.

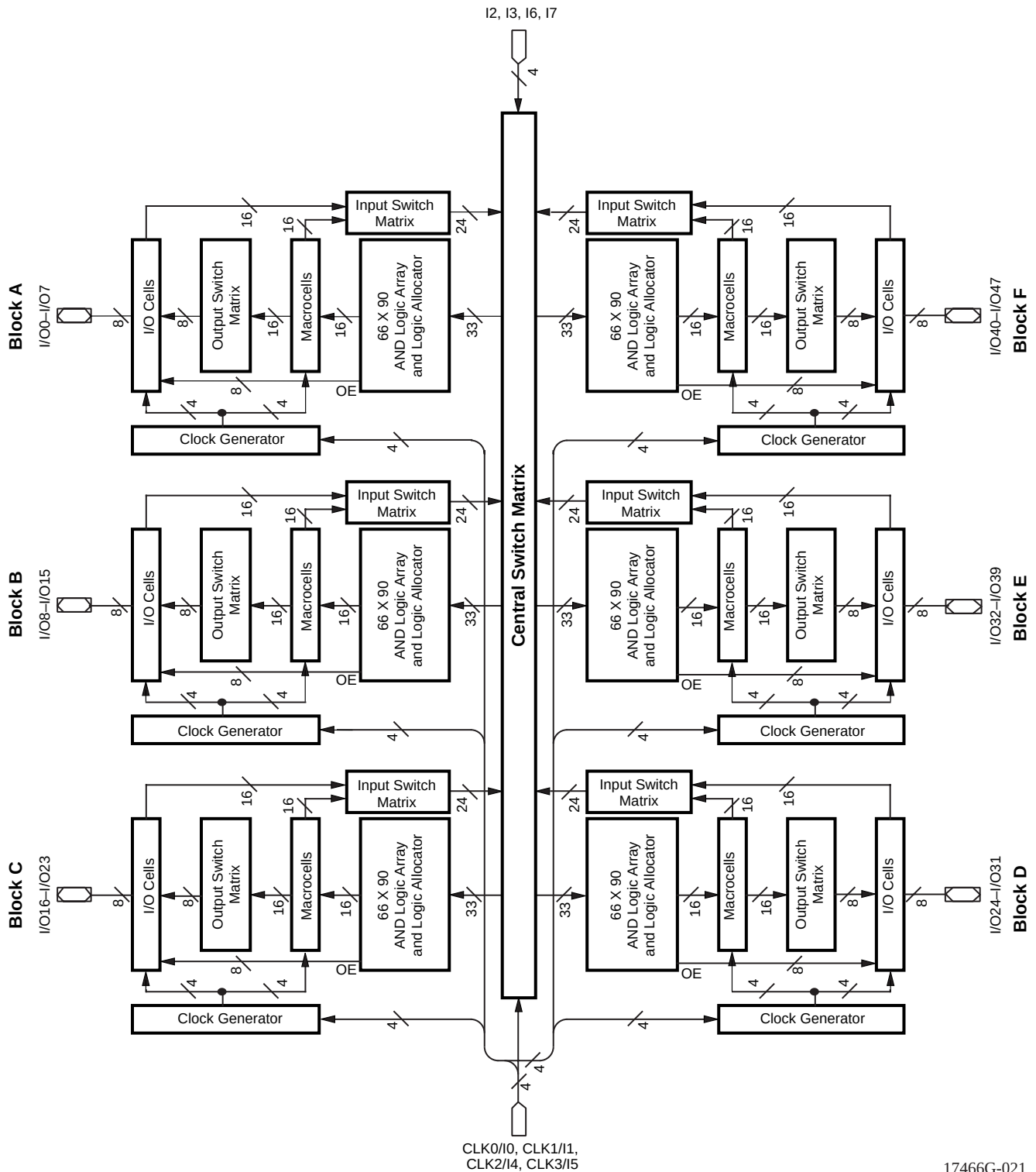
This feature provides high flexibility for partitioning state machines and dual-phase clocks. It also allows latches to be driven with either polarity of latch enable, and in a master-slave configuration.

BLOCK DIAGRAM – M4A(3,5)-64/32



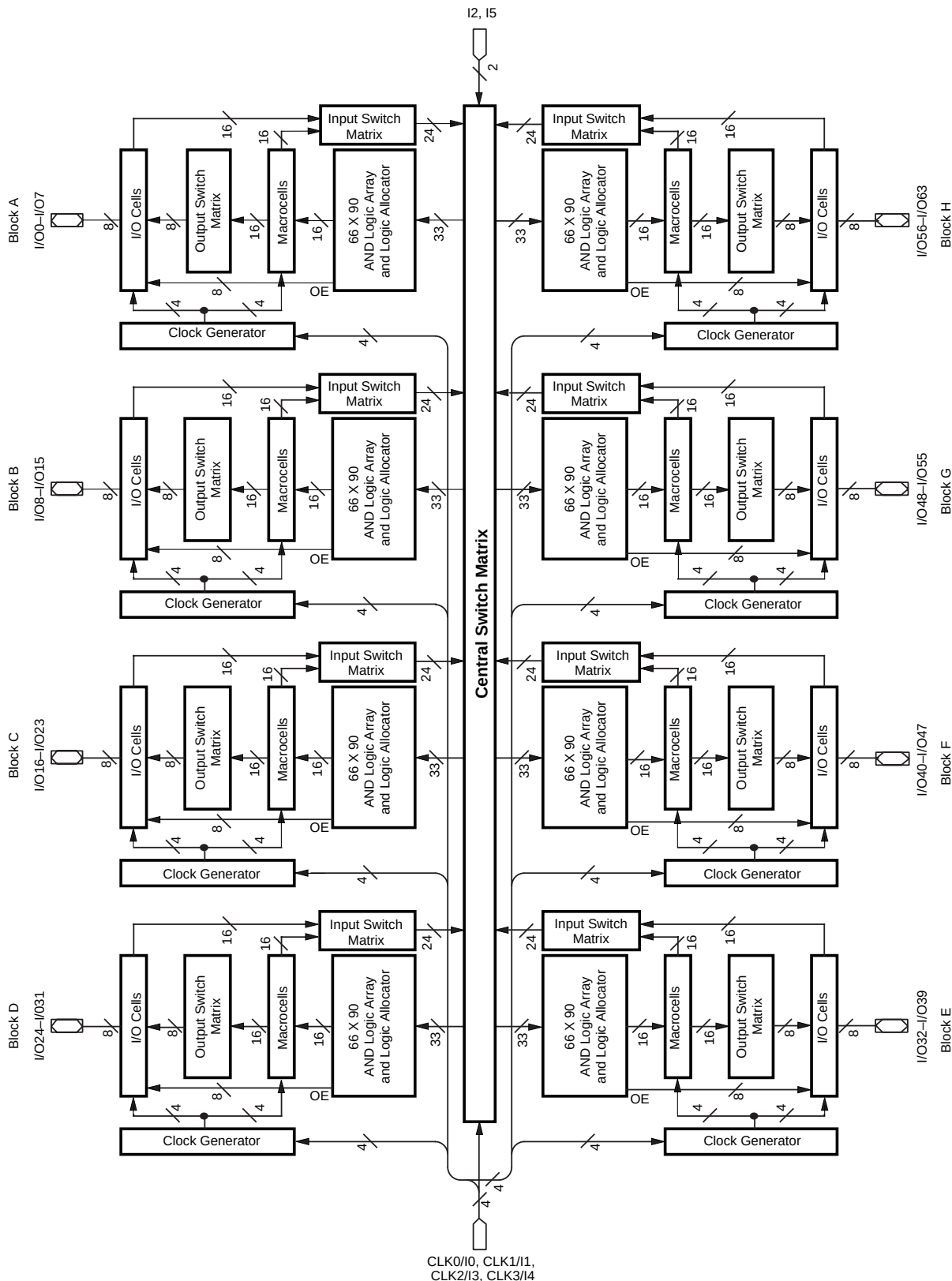
17466H-020

BLOCK DIAGRAM – M4A(3,5)-96/48



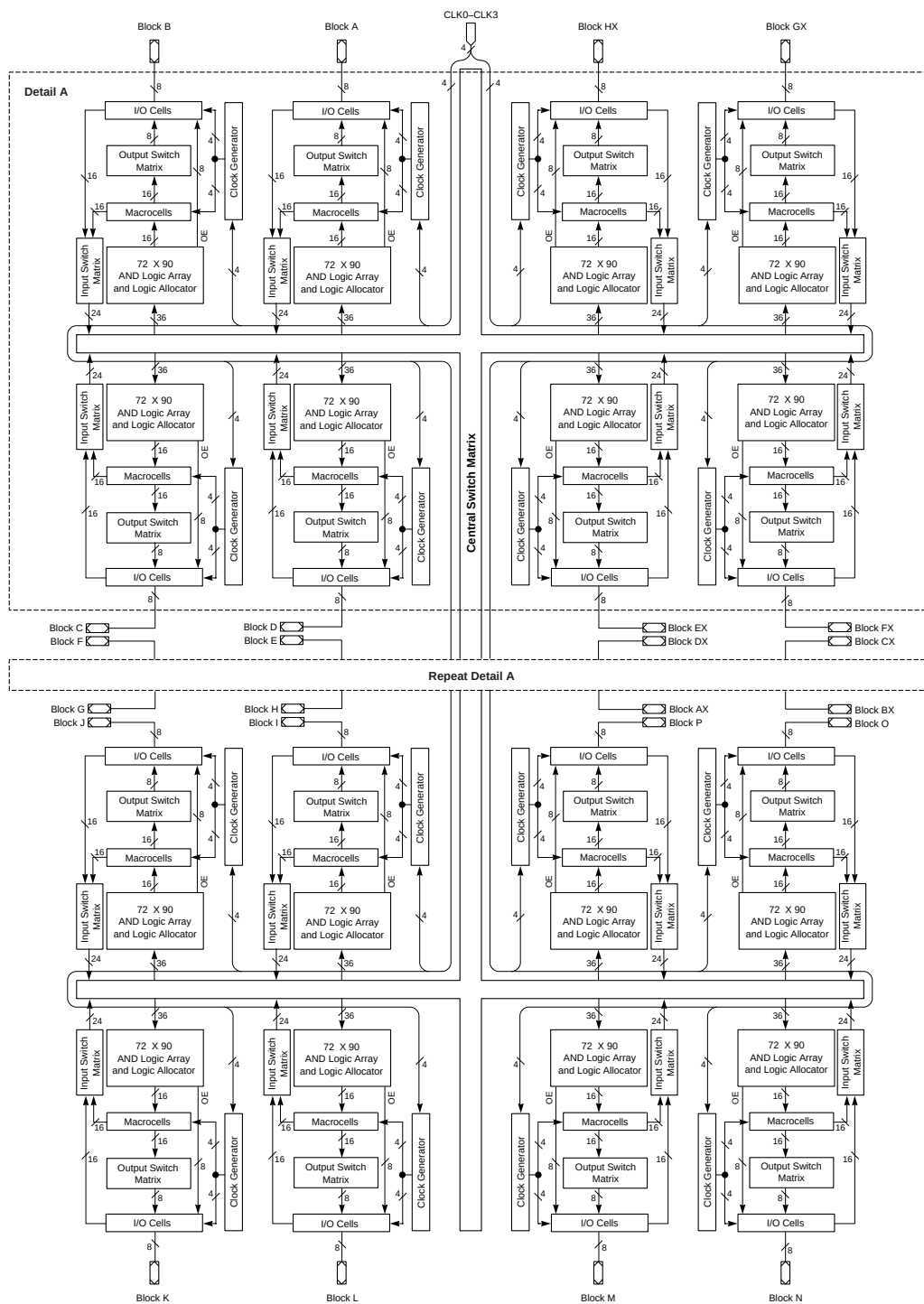
17466G-021

BLOCK DIAGRAM – M4A(3,5)-128/64



17466H-022

BLOCK DIAGRAM – M4A3-384/160, M4A3-384/192



17466G-067

ABSOLUTE MAXIMUM RATINGS

M4A3

Storage Temperature. -65°C to +150°C
 Ambient Temperature
 with Power Applied. -55°C to +100°C
 Device Junction Temperature. +130°C
 Supply Voltage
 with Respect to Ground. -0.5 V to +4.5 V
 DC Input Voltage. -0.5 V to 6.0 V
 Static Discharge Voltage. 2000 V
 Latchup Current ($T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$) 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)
 Operating in Free Air. 0°C to $+70^\circ\text{C}$
 Supply Voltage (V_{CC})
 with Respect to Ground. +3.0 V to +3.6 V

Industrial (I) Devices

Ambient Temperature (T_A)
 Operating in Free Air. -40°C to $+85^\circ\text{C}$
 Supply Voltage (V_{CC})
 with Respect to Ground. +3.0 V to +3.6 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

3.3-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions		Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	$V_{CC} = \text{Min}$ $V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = -100\ \mu\text{A}$	$V_{CC} - 0.2$			V
			$I_{OH} = -3.2\ \text{mA}$	2.4			V
V_{OL}	Output LOW Voltage	$V_{CC} = \text{Min}$ $V_{IN} = V_{IH}$ or V_{IL} (Note 1)	$I_{OL} = 100\ \mu\text{A}$			0.2	V
			$I_{OL} = 24\ \text{mA}$			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs		2.0		5.5	V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs		-0.3		0.8	V
I_{IH}	Input HIGH Leakage Current	$V_{IN} = 3.6\ \text{V}$, $V_{CC} = \text{Max}$ (Note 2)				5	μA
I_{IL}	Input LOW Leakage Current	$V_{IN} = 0\ \text{V}$, $V_{CC} = \text{Max}$ (Note 2)				-5	μA
I_{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 3.6\ \text{V}$, $V_{CC} = \text{Max}$ $V_{IN} = V_{IH}$ or V_{IL} (Note 2)				5	μA
I_{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0\ \text{V}$, $V_{CC} = \text{Max}$ $V_{IN} = V_{IH}$ or V_{IL} (Note 2)				-5	μA
I_{SC}	Output Short-Circuit Current	$V_{OUT} = 0.5\ \text{V}$, $V_{CC} = \text{Max}$ (Note 3)		-15		-160	mA

Notes:

1. Total I_{OL} for one PAL block should not exceed 64 mA.
2. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

Notes:

1. See "MACH Switching Test Circuit" document on the Literature Download page of the Lattice web site.
2. This parameter does not apply to flip-flops in the emulated mode since the feedback path is required for emulation.

ispMACH 4A TIMING PARAMETERS OVER OPERATING RANGES¹

		-5		-55		-6		-65		-7		-10		-12		-14		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Combinatorial Delay:																		
t _{PDi}	Internal combinatorial propagation delay		3.5		4.0		4.3		4.5		5.0		7.0		9.0		11.0	ns
t _{PD}	Combinatorial propagation delay		5.0		5.5		6.0		6.5		7.5		10.0		12.0		14.0	ns
Registered Delays:																		
t _{SS}	Synchronous clock setup time, D-type register	3.0		3.5		3.5		3.5		5.0		5.5		7.0		10.0		ns
t _{SST}	Synchronous clock setup time, T-type register	4.0		4.0		4.0		4.0		6.0		6.5		8.0		11.0		ns
t _{SA}	Asynchronous clock setup time, D-type register	2.5		2.5		2.5		3.0		3.5		4.0		5.0		8.0		ns
t _{SAT}	Asynchronous clock setup time, T-type register	3.0		3.0		3.0		3.5		4.5		5.0		6.0		9.0		ns
t _{HS}	Synchronous clock hold time	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t _{HA}	Asynchronous clock hold time	2.5		2.5		2.5		3.0		3.5		4.0		5.0		8.0		ns
t _{COSi}	Synchronous clock to internal output		2.5		2.5		2.8		3.0		3.0		3.0		3.5		3.5	ns
t _{COS}	Synchronous clock to output		4.0		4.0		4.5		5.0		5.5		6.0		6.5		6.5	ns
t _{COAi}	Asynchronous clock to internal output		5.0		5.0		5.0		5.0		6.0		8.0		10.0		12.0	ns
t _{COA}	Asynchronous clock to output		6.5		6.5		6.8		7.0		8.5		11.0		13.0		15.0	ns
Latched Delays:																		
t _{SSL}	Synchronous latch setup time	4.0		4.0		4.0		4.5		6.0		7.0		8.0		10.0		ns
t _{SAL}	Asynchronous latch setup time	3.0		3.0		3.5		3.5		4.0		4.0		5.0		8.0		ns
t _{HSL}	Synchronous latch hold time	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t _{HAL}	Asynchronous latch hold time	3.0		3.0		3.5		3.5		4.0		4.0		5.0		8.0		ns
t _{PDLi}	Transparent latch to internal output		5.5		5.5		5.8		6.0		7.5		9.0		11.0		12.0	ns
t _{PDL}	Propagation delay through transparent latch to output		7.0		7.0		7.5		8.0		10.0		12.0		14.0		15.0	ns
t _{GOSi}	Synchronous gate to internal output		3.0		3.0		3.0		3.0		3.5		4.5		7.0		8.0	ns
t _{GOS}	Synchronous gate to output		4.5		4.5		4.8		5.0		6.0		7.5		10.0		11.0	ns
t _{GOAi}	Asynchronous gate to internal output		6.0		6.0		6.0		6.0		8.5		10.0		13.0		15.0	ns
t _{GOA}	Asynchronous gate to output		7.5		7.5		7.8		8.0		11.0		13.0		16.0		18.0	ns
Input Register Delays:																		
t _{SIRS}	Input register setup time	1.5		1.5		2.0		2.0		2.0		2.0		2.0		2.0		ns
t _{HIRS}	Input register hold time	2.5		2.5		3.0		3.0		3.0		3.0		3.0		4.0		ns
t _{ICOSi}	Input register clock to internal feedback		3.0		3.0		3.0		3.0		3.5		4.5		6.0		6.0	ns
Input Latch Delays:																		
t _{SIL}	Input latch setup time	1.5		1.5		1.5		2.0		2.0		2.0		2.0		2.0		ns
t _{HIL}	Input latch hold time	2.5		2.5		2.5		3.0		3.0		3.0		3.0		4.0		ns
t _{IGOSi}	Input latch gate to internal feedback		3.5		3.5		3.8		4.0		4.0		4.0		4.0		5.0	ns
t _{PDILi}	Transparent input latch to internal feedback		1.5		1.5		1.5		1.5		2.0		2.0		2.0		2.0	ns

ispMACH 4A TIMING PARAMETERS OVER OPERATING RANGES¹

		-5		-55		-6		-65		-7		-10		-12		-14		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Frequency:																		
f _{MAXS}	External feedback, D-type, Min of 1/(t _{WLS} + t _{WHS}) or 1/(t _{SS} + t _{COS})	143		133		125		118		95.2		87.0		74.1		60.6		MHz
	External feedback, T-type, Min of 1/(t _{WLS} + t _{WHS}) or 1/(t _{SST} + t _{COS})	125		125		118		111		87.0		80.0		69.0		57.1		MHz
	Internal feedback (f _{CNT}), D-type, Min of 1/(t _{WLS} + t _{WHS}) or 1/(t _{SS} + t _{COSi})	182		167		160		154		125		118		95.0		74.1		MHz
	Internal feedback (f _{CNT}), T-type, Min of 1/(t _{WLS} + t _{WHS}) or 1/(t _{SST} + t _{COSi})	154		154		148		143		111		105		87.0		69.0		MHz
	No feedback ² , Min of 1/(t _{WLS} + t _{WHS}), 1/(t _{SS} + t _{HS}) or 1/(t _{SST} + t _{HS})	250		250		200		200		154		125		100		83.3		MHz
f _{MAXA}	External feedback, D-type, Min of 1/(t _{WLA} + t _{WHA}) or 1/(t _{SA} + t _{COA})	111		111		108		100		83.3		66.7		55.6		43.5		MHz
	External feedback, T-type, Min of 1/(t _{WLA} + t _{WHA}) or 1/(t _{SAT} + t _{COA})	105		105		102		95.2		76.9		62.5		52.6		41.7		MHz
	Internal feedback (f _{CNTA}), D-type, Min of 1/(t _{WLA} + t _{WHA}) or 1/(t _{SA} + t _{COAi})	133		133		125		125		105		83.3		66.7		50.0		MHz
	Internal feedback (f _{CNTA}), T-type, Min of 1/(t _{WLA} + t _{WHA}) or 1/(t _{SAT} + t _{COAi})	125		125		125		118		95.2		76.9		62.5		47.6		MHz
	No feedback ² , Min of 1/(t _{WLA} + t _{WHA}), 1/(t _{SA} + t _{HA}) or 1/(t _{SAT} + t _{HA})	167		167		143		143		125		100		62.5		55.6		MHz
f _{MAXI}	Maximum input register frequency, Min of 1/(t _{WIRH} + t _{WIRL}) or 1/(t _{SIRS} + t _{HIRS})	167		167		143		143		125		100		83.3		83.3		MHz

Notes:

1. See "Switching Test Circuit" document on the Literature Download page of the Lattice web site.
2. This parameter does not apply to flip-flops in the emulated mode since the feedback path is required for emulation.

CAPACITANCE¹

Parameter Symbol	Parameter Description	Test Conditions		Typ	Unit
C_{IN}	Input capacitance	$V_{IN}=2.0\text{ V}$	3.3 V or 5 V, 25°C, 1 MHz	6	pF
$C_{I/O}$	Output capacitance	$V_{OUT}=2.0\text{ V}$	3.3 V or 5 V, 25°C, 1 MHz	8	pF

Note:

1. These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where this parameter may be affected.

I_{CC} vs. FREQUENCY

These curves represent the typical power consumption for a particular device at system frequency. The selected “typical” pattern is a 16-bit up-down counter. This pattern fills the device and exercises every macrocell. Maximum frequency shown uses internal feedback and a D-type register. Power/Speed are optimized to obtain the highest counter frequency and the lowest power. The highest frequency (LSBs) is placed in common PAL blocks, which are set to high power. The lowest frequency signals (MSBs) are placed in a common PAL block and set to lowest power.

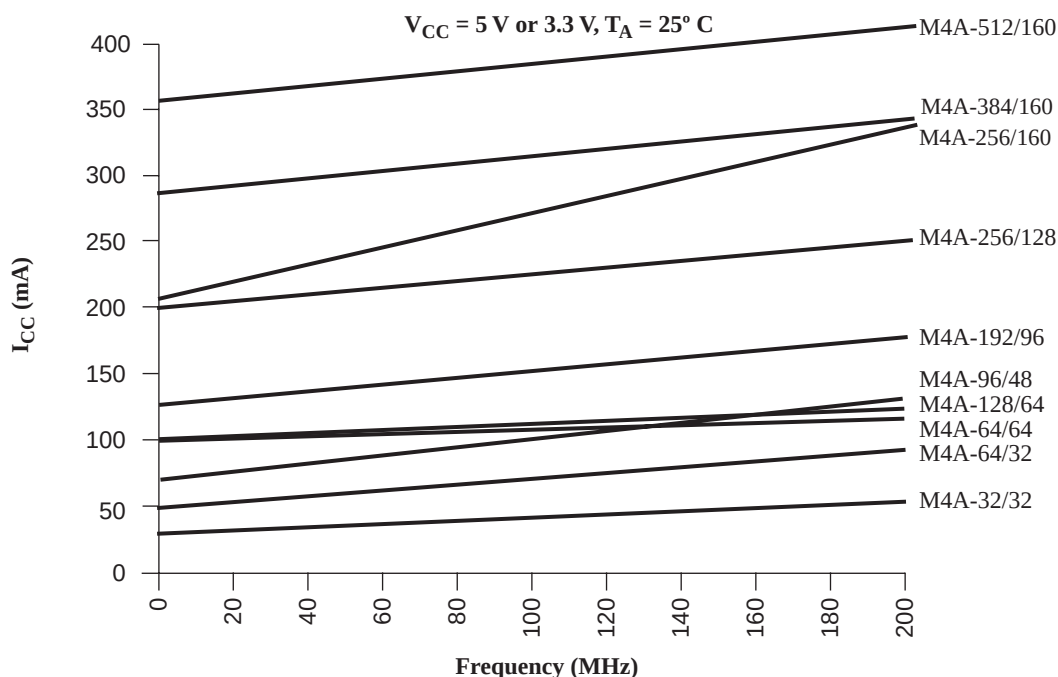


Figure 19. ispMACH 4A I_{CC} Curves at High Speed Mode

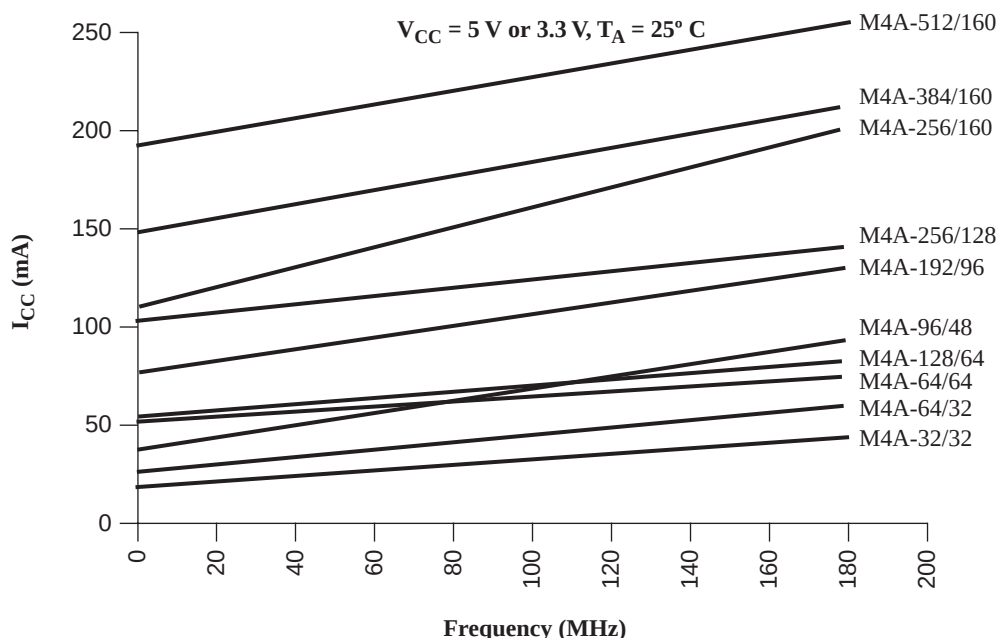


Figure 20. ispMACH 4A I_{CC} Curves at Low Power Mode

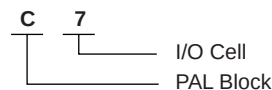
144-BALL FPBGA CONNECTION DIAGRAM (M4A3-192/96)

Bottom View

144-Ball fpBGA													
	12	11	10	9	8	7	6	5	4	3	2	1	
A	GND	I/O72 L7	I/O76 L3	I13	GBCLK3	I0	I/O82 A2	I/O86 A6	I/O88 B0	I/O93 B5	I/O95 B7	GND	A
B	GND	I/O73 L6	I/O77 L2	I/O79 L0	VCC	I1	I/O83 A3	I/O87 A7	I/O90 B2	I/O94 B6	I/O0 D7	TDI	B
C	GND	TD0	I/O74 L5	I14	GND	I/O80 A0	I/O84 A4	GND	I/O92 B4	I/O1 D6	I/O4 D3	I/O3 D4	C
D	I/O67 K4	I/O69 K2	I/O71 K0	I/O75 L4	GBCLK0	I/O81 A1	VCC	I/O91 B3	I/O2 D5	I2	I/O6 D1	I/O7 D0	D
E	I12	I/O64 K7	I/O66 K5	I/O70 K1	I/O78 L1	I/O85 A5	I/O89 B1	I/O5 D2	I/O8 C7	I4	GND	VCC	E
F	I10	I11	GND	I/O65 K6	I/O68 K3	I15	I3	GND	I/O12 C3	I/O11 C4	I/O10 C5	I/O9 C6	F
G	I/O60 J3	I/O61 J2	I/O62 J1	I/O63 J0	VCC	GND	I7	I/O20 E3	I/O17 E6	I/O15 C0	I/O14 C1	I/O13 C2	G
H	I/O56 J7	I/O57 J6	I/O58 J5	I/O59 J4	I/O53 I2	I/O41 H1	I/O37 G5	I/O30 F1	I/O22 E1	I/O18 E5	I/O16 E7	VCC	H
J	I/O55 I0	I/O54 I1	VCC	I/O50 I5	I/O43 H3	VCC	I/O33 G1	GBCLK2	I/O27 F4	I/O23 E0	I/O21 E2	I/O19 E4	J
K	I/O51 I4	I/O52 I3	I/O49 I6	I/O44 H4	GND	I/O36 G4	I/O32 G0	VCC	I6	I/O26 F5	TCK	TMS	K
L	GND	I/O48 I7	I/O46 H6	I/O42 H2	I/O39 G7	I/O35 G3	I9	GND	I/O31 F0	I/O29 F2	I/O25 F6	GND	L
M	GND	I/O47 H7	I/O45 H5	I/O40 H0	I/O38 G6	I/O34 G2	I8	GBCLK1	I5	I/O28 F3	I/O24 F7	GND	M
	12	11	10	9	8	7	6	5	4	3	2	1	

PIN DESIGNATIONS

CLK = Clock
 GND = Ground
 I = Input
 I/O = Input/Output
 N/C = No Connect
 VCC = Supply Voltage
 TDI = Test Data In
 TCK = Test Clock
 TMS = Test Mode Select
 TD0 = Test Data Out

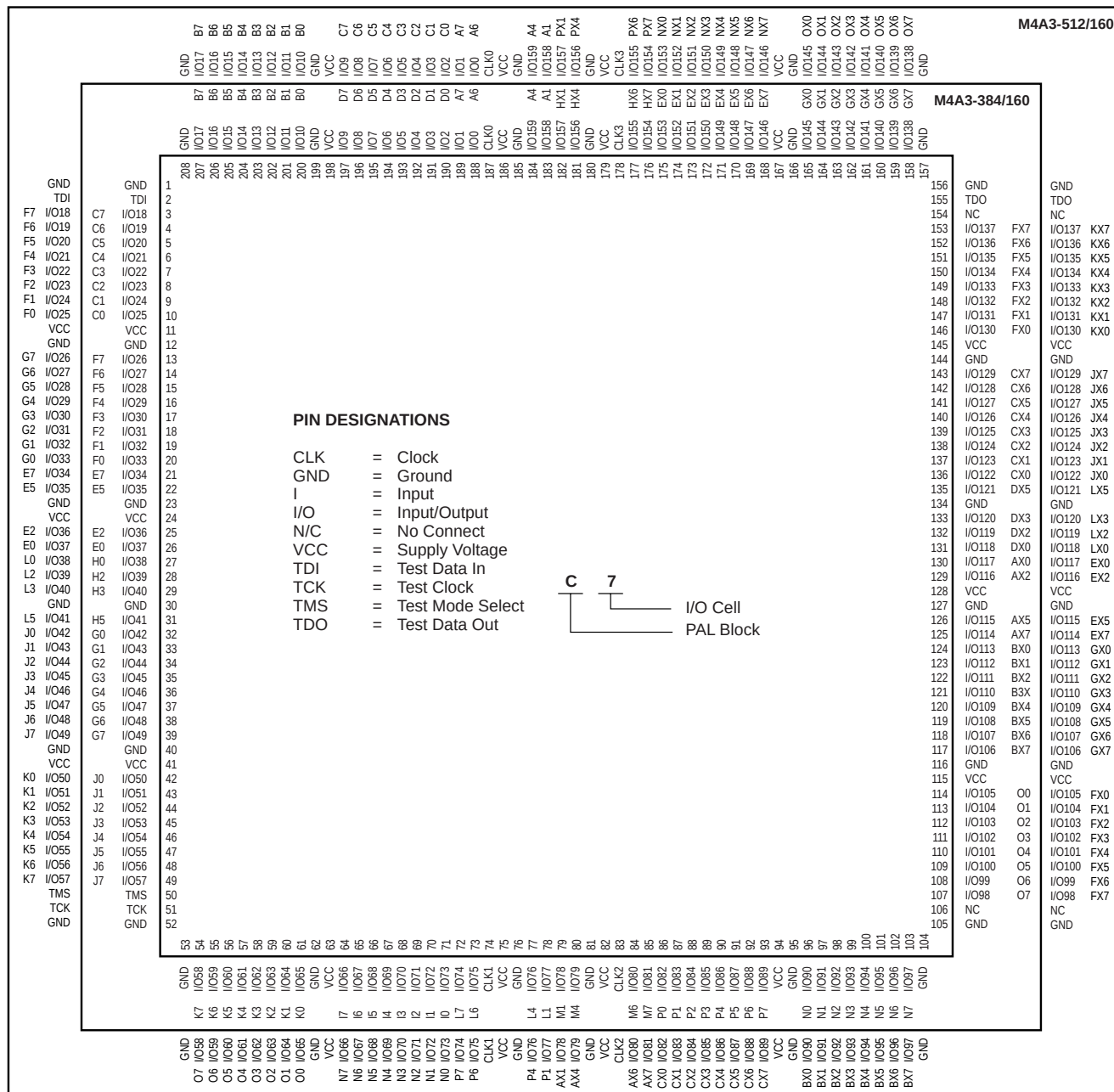


m4a3.192.96_144bga

208-PIN PQFP CONNECTION DIAGRAM (M4A3-384/160 AND M4A3-512/160)

Top View

208-Pin PQFP



17466Ga-044

256-BALL fpBGA CONNECTION DIAGRAM (M4A3-384/192)

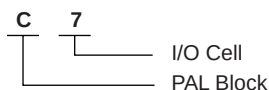
Bottom View

256-Ball fpBGA

	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	I/O175 FX7	I/O181 GX5	I/O180 GX4	I/O177 GX1	I/O166 EX6	I/O164 EX4	I/O191 HX7	I/O186 HX2	I/O1 A1	I/O3 A3	CLK0	I/O25 D1	I/O29 D5	I/O31 D7	I/O10 B2	I/O12 B4	A
B	I/O173 FX5	I/O174 FX6	I/O182 GX6	I/O179 GX3	I/O167 EX7	I/O165 EX5	I/O160 EX0	I/O187 HX3	I/O0 A0	I/O5 A5	I/O7 A7	I/O26 D2	I/O8 B0	I/O11 B3	I/O13 B5	N/C	B
C	I/O171 FX3	I/O172 FX4	N/C	I/O183 GX7	I/O178 GX2	I/O162 EX2	I/O163 EX3	I/O189 HX5	I/O184 HX0	I/O6 A6	I/O28 D4	I/O30 D6	I/O15 B7	I/O14 B6	TDI	I/O23 C7	C
D	I/O150 CX6	I/O151 CX7	TDO	GND	GND	VCC	GND	VCC	GND	GND	VCC	GND	VCC	I/O9 B1	I/O22 C6	I/O21 C5	D
E	I/O148 CX4	N/C	I/O170 FX2	VCC	I/O168 FX0	169 FX1	I/O190 HX6	CLK3	I/O188 HX4	I/O2 A2	I/O24 D0	N/C	GND	I/O20 C4	I/O19 C3	I/O47 F7	E
F	I/O144 CX0	I/O149 CX5	I/O147 CX3	GND	I/O146 CX2	I/O145 CX1	I/O176 GX0	I/O161 EX1	I/O185 HX1	I/O4 A4	I/O27 D3	I/O18 C2	VCC	I/O16 C0	I/O46 F6	I/O45 F5	F
G	I/O155 DX3	I/O158 DX6	I/O157 DX5	VCC	I/O156 DX4	I/O159 DX7	VCC	GND	GND	VCC	I/O17 C1	I/O44 F4	GND	I/O42 F2	I/O41 F1	I/O39 E7	G
H	I/O152 DX0	I/O154 DX2	I/O153 DX1	GND	I/O128 AX0	I/O129 AX1	GND	VCC	VCC	GND	I/O43 F3	I/O40 F0	VCC	I/O36 E4	I/O35 E3	I/O34 E2	H
J	I/O130 AX2	I/O131 AX3	I/O132 AX4	GND	I/O134 AX6	I/O133 AX5	GND	VCC	VCC	GND	I/O38 E6	I/O37 E5	GND	I/O57 H1	I/O56 H0	I/O58 H2	J
K	I/O135 AX7	I/O136 BX0	I/O137 BX1	VCC	I/O139 BX3	I/O138 BX2	VCC	GND	GND	VCC	I/O33 E1	I/O32 E0	VCC	I/O63 H7	I/O62 H6	I/O48 G0	K
L	I/O140 BX4	I/O141 BX5	I/O143 BX7	GND	I/O114 O2	I/O142 BX6	I/O98 M2	I/O91 L3	I/O67 I3	I/O69 I5	I/O60 H4	I/O59 H3	GND	I/O51 G3	I/O52 G4	I/O49 G1	L
M	I/O112 O0	I/O113 O1	I/O115 O3	GND	I/O123 P3	I/O121 P1	I/O100 M4	I/O90 L2	I/O66 I2	I/O80 K0	I/O83 K3	I/O61 H5	VCC	I/O76 J4	I/O55 G7	I/O50 G2	M
N	I/O116 O4	I/O117 O5	I/O119 O7	VCC	GND	VCC	GND	VCC	GND	GND	VCC	GND	GND	TCK	I/O72 J0	I/O53 G5	N
P	I/O118 O6	I/O109 N5	I/O110 N6	I/O111 N7	I/O124 P4	I/O122 P2	I/O101 M5	I/O89 L1	I/O93 L5	I/O94 L6	I/O71 I7	I/O84 K4	I/O87 K7	TMS	I/O73 J1	I/O54 G6	P
R	I/O108 N4	I/O107 N3	I/O104 N0	I/O127 P7	I/O120 P0	I/O102 M6	I/O99 M3	I/O96 M0	I/O92 L4	I/O64 I0	I/O68 I4	I/O81 K1	I/O85 K5	I/O79 J7	I/O75 J3	I/O74 J2	R
T	I/O106 N2	I/O105 N1	I/O126 P6	I/O125 P5	I/O103 M7	CLK2	I/O97 M1	I/O88 L0	CLK1	I/O95 L7	I/O65 I1	I/O70 I6	I/O82 K2	I/O86 K6	I/O78 J6	I/O77 J5	T
	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

PIN DESIGNATIONS

CLK = Clock
 GND = Ground
 I = Input
 I/O = Input/Output
 N/C = No Connect
 VCC = Supply Voltage
 TDI = Test Data In
 TCK = Test Clock
 TMS = Test Mode Select
 TDO = Test Data Out



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256-BALL fpBGA CONNECTION DIAGRAM (M4A3-512/192)

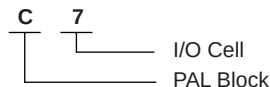
Bottom View

256-Ball fpBGA

	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	I/O159 KX7	I/O181 OX5	I/O180 OX4	I/O177 OX1	I/O174 NX6	I/O172 NX4	I/O191 PX7	I/O186 PX2	I/O1 A1	I/O3 A3	CLK0	I/O17 C1	I/O21 C5	I/O23 C7	I/O10 B2	I/O12 B4	A
B	I/O157 KX5	I/O158 KX6	I/O182 OX6	I/O179 OX3	I/O175 NX7	I/O173 NX5	I/O168 NX0	I/O187 PX3	I/O0 A0	I/O5 A5	I/O7 A7	I/O18 C2	I/O8 B0	I/O11 B3	I/O13 B5	N/C	B
C	I/O155 KX3	I/O156 KX4	N/C	I/O183 OX7	I/O178 OX2	I/O170 NX2	I/O171 NX3	I/O189 PX5	I/O184 PX0	I/O6 A6	I/O20 C4	I/O22 C6	I/O15 B7	I/O14 B6	TDI	I/O39 F7	C
D	I/O150 JX6	I/O151 JX7	TDO	GND	GND	VCC	GND	VCC	GND	GND	VCC	GND	VCC	I/O9 B1	I/O38 F6	I/O37 F5	D
E	I/O148 JX4	N/C	I/O154 KX2	VCC	I/O152 KX0	I/O153 KX1	I/O190 PX6	CLK3	I/O188 PX4	I/O2 A2	I/O16 C0	N/C	GND	I/O36 F4	I/O35 F3	I/O47 G7	E
F	I/O144 JX0	I/O149 JX5	I/O147 JX3	GND	I/O146 JX2	I/O145 JX1	I/O176 OX0	I/O169 NX1	I/O185 PX1	I/O4 A4	I/O19 C3	I/O34 F2	VCC	I/O32 F0	I/O46 G6	I/O45 G5	F
G	I/O163 LX3	I/O166 LX6	I/O165 LX5	VCC	I/O164 LX4	I/O167 LX7	VCC	GND	GND	VCC	I/O33 F1	I/O44 G4	GND	I/O42 G2	I/O41 G1	I/O31 E7	G
H	I/O160 LX0	I/O162 LX2	I/O161 LX1	GND	I/O120 EX0	I/O121 EX1	GND	VCC	VCC	GND	I/O43 G3	I/O40 G0	VCC	I/O28 E4	I/O27 E3	I/O26 E2	H
J	I/O122 EX2	I/O123 EX3	I/O124 EX4	GND	I/O126 EX6	I/O125 EX5	GND	VCC	VCC	GND	I/O30 E6	I/O29 E5	GND	I/O65 L1	I/O64 L0	I/O66 L2	J
K	I/O127 EX7	I/O136 GX0	I/O137 GX1	VCC	I/O139 GX3	I/O138 GX2	VCC	GND	GND	VCC	I/O25 E1	I/O24 E0	VCC	I/O71 L7	I/O70 L6	I/O48 J0	K
L	I/O140 GX4	I/O141 GX5	I/O143 GX7	GND	I/O130 FX2	I/O142 GX6	I/O98 AX2	I/O91 P3	I/O75 N3	I/O77 N5	I/O68 L4	I/O67 L3	GND	I/O51 J3	I/O52 J4	I/O49 J1	L
M	I/O128 FX0	I/O129 FX1	I/O131 FX3	GND	I/O115 CX3	I/O113 CX1	I/O100 AX4	I/O90 P2	I/O74 N2	I/O80 O0	I/O83 O3	I/O69 L5	VCC	I/O60 K4	I/O55 J7	I/O50 J2	M
N	I/O132 FX4	I/O133 FX5	I/O135 FX7	VCC	GND	VCC	GND	VCC	GND	GND	VCC	GND	GND	TCK	I/O56 K0	I/O53 J5	N
P	I/O134 FX6	I/O109 BX5	I/O110 BX6	I/O111 BX7	I/O116 CX4	I/O114 CX2	I/O101 AX5	I/O89 P1	I/O93 P5	I/O94 P6	I/O79 N7	I/O84 O4	I/O87 O7	TMS	I/O57 K1	I/O54 J6	P
R	I/O108 BX4	I/O107 BX3	I/O104 BX0	I/O119 CX7	I/O112 CX0	I/O102 AX6	I/O99 AX3	I/O96 AX0	I/O92 P4	I/O72 N0	I/O76 N4	I/O81 O1	I/O85 O5	I/O63 K7	I/O59 K3	I/O58 K2	R
T	I/O106 BX2	I/O105 BX1	I/O118 CX6	I/O117 CX5	I/O103 AX7	CLK2	I/O97 AX1	I/O88 P0	CLK1	I/O95 P7	I/O73 N1	I/O78 N6	I/O82 O2	I/O86 O6	I/O62 K6	I/O61 K5	T
	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

PIN DESIGNATIONS

CLK = Clock
 GND = Ground
 I = Input
 I/O = Input/Output
 N/C = No Connect
 VCC = Supply Voltage
 TDI = Test Data In
 TCK = Test Clock
 TMS = Test Mode Select
 TDO = Test Data Out



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